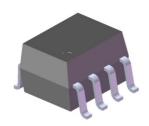


DATASHEET

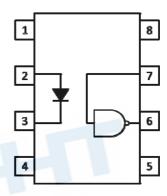
8 PIN SOP HIGH SPEED 10MBit/s LOGIC GATE PHOTOCOUPLER EL06XX Series



Features

- Compliance Halogen Free (Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)
- High speed 10Mbit/s
- 10kV/µs minimum commone mode transient immunity at VCM= 1KV (EL0611)
- Guaranteed performance from -40 to 85°C
- Wide operating temperature range of -40°C to 100°C
- Logic gate output
- High isolation voltage between input and output (Viso=3750 V rms)
- Compliance with EU REACH
- Pb free and RoHS compliant.
- UL and cUL approved (No. E214129)
- VDE approved (No. 40028116)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved

Schematic



A 0.1µF bypass capacitor must be connected between pins 8 and 5 *3

Pin Configuration

- 1, No Connection
- 2, Anode
- 3, Cathode
- 4. No Connection
- 5, Gnd
- 6, Vout
- 7, V_E
- 8, Vcc

Description

The EL0600, EL0601 and EL0611 devices each consists of an infrared emitting diode optically coupled to a high speed integrated photo detector logic gate with a strobable output.

The devices are packaged in an 8-pin small outline package which conforms to the standard SO8 footprint.

Applications

- Ground loop elimination
- LSTTL to TTL, LSTTL or 5 volt CMOS
- Line receiver, data transmission
- Data multiplexing
- Switching power supplies
- Pulse transformer replacement
- Computer peripheral interface
- High speed logic ground isolation

Truth Table (Positive Logic)

Enable	Output
Н	L
Н	Н
L	Н
L	Н
NC	L
NC	Н
	Enable H H L L NC



Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
	Forward current	l _F	20	mA
Input	Enable input voltage Not exceed V _{CC} by more than 500mV		5.5	V
put	Reverse voltage	V_{R}	5	V
	Power dissipation	P_D	40	mW
	Power dissipation		85	mW
0 1 1	Enable input current	Ι _Ε	5	mA
Output	Output current Output voltage		50	mA
			7.0	V
Output Power Dissipation		Po	100	mW
Isolation voltage *1		V _{ISO}	3750	V rms
Operating temperature		T _{OPR}	-40 ~ +100	°C
Storage temperature		T _{STG}	-55 ~ +125	°C
Soldering	g temperature *2	T _{SOL}	260	°C

Notes:

^{*1} AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2, 3 & 4 are shorted together, and pins 5, 6, 7 & 8 are shorted together.

^{*2} For 10 seconds.



Electrical Characteristics (Ta=-40 to 85°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward voltage	V_{F}	-	1.4	1.8	V	I _F = 10mA
Reverse voltage	V_R	5.0	-	-	V	I _R = 10μA
Temperature coefficient of forward voltage	$\Delta V_F / \Delta T_A$	-	-1.8	-	mV/°C	I _F =10mA
Input capacitance	C_{IN}	-	60	-	pF	V _F =0, f=1MHz

Note: Reverse Voltage(VR) Condition is applied to IR test only The device is not designed for reverse operation

Output

Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
High level supply current	Іссн	-	-	10	mA	I _F =0mA, V _E =0.5V, V _{CC} =5.5V
Low level supply current	Iccl	-	-	13	mA	I _F =10mA, V _E =0.5V, V _{CC} =5.5V
High level enable current	I _{EH}	-	-	-1.6	mA	V _E =2.0V, V _{CC} =5.5V
Low level enable current	lEL	1	RIL	-1.6	mA	V _E =0.5V, V _{CC} =5.5V
High level enable voltage	V _{ЕН}	2.0		-	V	I _F =10mA, V _{CC} =5.5V
Low level enable voltage*4	V _{EL}	-	-	0.8	V	I _F =10mA, V _{CC} =5.5V

Transfer Characteristics (Ta=-40 to 85°C unless specified otherwise)

Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
HIGH Level Output Current	Іон	-	-	100	uA	V _{CC} =5.5V, V _O =5.5V, I _F =250μA, V _E =2.0V
LOW Level Output Current	V_{OL}	-	-	0.6	V	$V_{CC} = 5.5V$, $I_F=5mA$, $V_E=2.0V$, $I_{CL}=13mA$
Input Threshold Current	lft	-	-	5	mA	V_{CC} = 5.5V, V_{O} =0.6V, V_{E} =2.0V, I_{OL} =13mA



Switching Characteristics (Ta=-40 to 85°C, Vcc=5V, I_F=7.5mA unless specified otherwise)

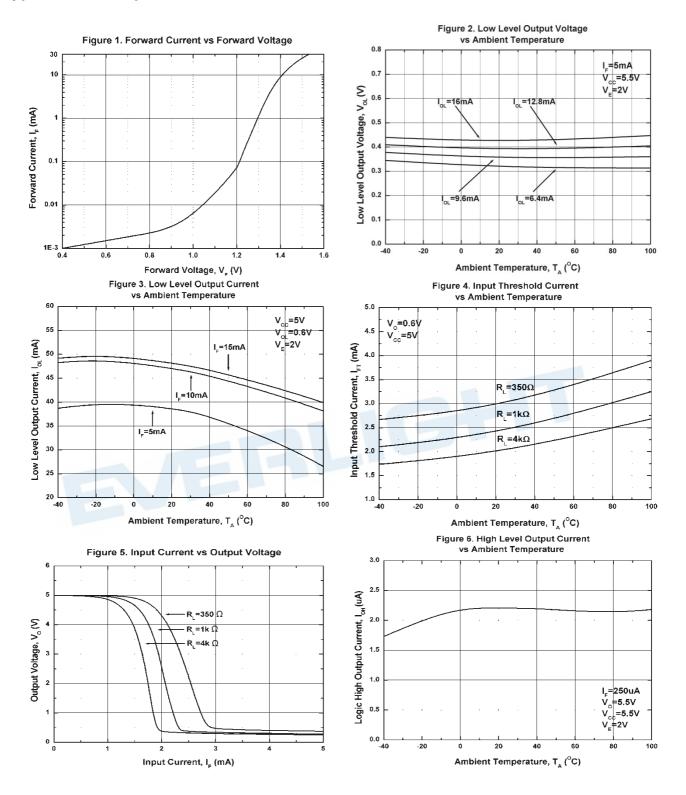
Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
Propagation delay time to output High level*5 (Fig.12)	T _{PHL}	-	35	75	ns	$C_L = 15 pF, R_L = 350 \Omega,$ TA=25°C
Propagation delay time to output Low level*6 (Fig.12)	Трін	-	45	75	ns	$C_L = 15pF, R_L = 350\Omega,$ TA=25°C
Pulse width distortion	Tphl – Tplh	-	10	35	ns	$C_L = 15pF, R_L = 350\Omega$
Output rise time* ⁷ (Fig.12)	tr	-	30	40	ns	$C_L = 15 pF, R_L = 350 \Omega$
Output fall time*8 (Fig.12)	tf	-	10	20	ns	$C_L = 15pF, R_L = 350\Omega$

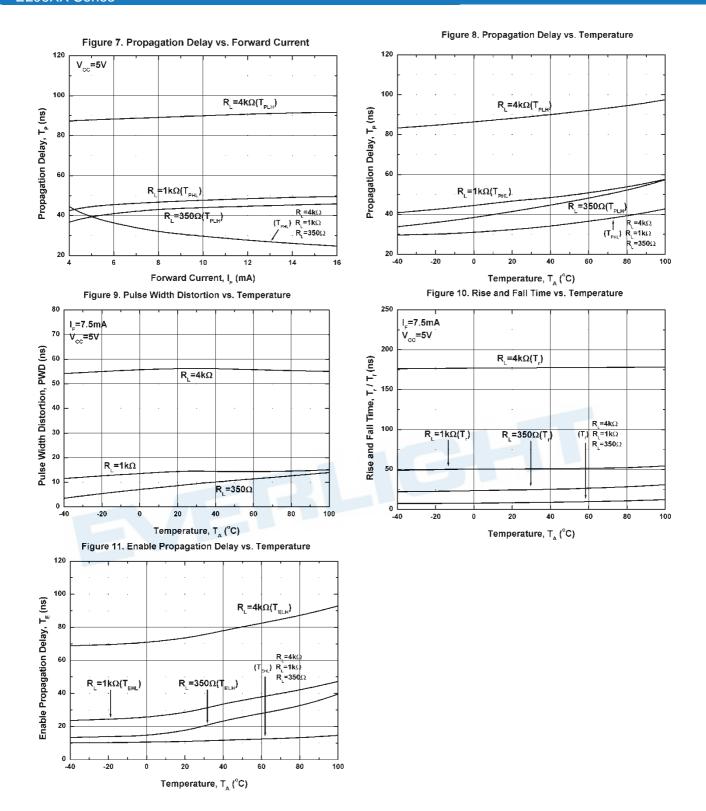
Switching Characteristics (T_a=-40 to 85°C, V_{CC}=5V, I_F=7.5mA unless specified otherwise)

Param	neter	Symbol	Min	Тур.	Max.	Unit	Condition
Enable Prop Delay Time High Level* (Fig.13)	to Output	t _{ELH}	-	30	40	ns	I_F = 7.5mA , V_{EH} =3V, C_L = 15pF, R_L =350 Ω
Enable Prop Delay Time Low Level* ¹ (Fig.13)	to Output	t _{EHL}		20	30	ns	I_F = 7.5mA , V_{EH} =3V, C_L = 15pF, R_L =350 Ω
	EL0600	Æ	Ed		-		I_F = 7.5mA , V_{OH} =2.0V, R_L =350 Ω , TA=25°C V_{CM} =10Vp-p (Fig.14)
Common Mode Transient	EL0601	СМн	5,000	-	-	V/µS	I_F = 7.5mA , V_{OH} =2.0V, R_L =350 Ω , TA=25°C V_{CM} =50Vp-p (Fig.14)
Immunity at Logic High ^{*11}			10,000	-	-		$\begin{split} I_{\text{F}} = 7.5 \text{mA} \;,\; V_{\text{OH}} = 2.0 \text{V}, \\ R_{\text{L}} = 350 \Omega,\; \text{TA} = 25 ^{\circ} \text{C} \\ V_{\text{CM}} = 400 \text{Vp-p} \; (\text{Fig.14}) \end{split}$
	EL0611		15,000	-	-		I_F = 7.5mA , V_{OH} =2.0V, R_L =350 Ω , TA=25°C V_{CM} =400Vp-p (Fig.15)
	EL0600		-	-	-		I_F = 0mA , V_{OL} = 0.8V, R_L = 350 Ω , TA = 25°C V_{CM} = 10Vp-p (Fig.14)
Common Mode Transient	EL0601	СМ∟	5,000			V/µS	I_F = 0mA , V_{OL} = 0.8V, R_L = 350 Ω , TA = 25°C V_{CM} = 50Vp-p (Fig.14)
Immunity at Logic Low *12	EL0611		10,000	ν/μΟ	$\begin{array}{c} I_F = 0 mA \;,\; V_{OL} = 0.8 V, \\ R_L = 350 \Omega ,\; TA = 25 ^{\circ} C \\ V_{CM} = 400 Vp - p \; (Fig. 14) \end{array}$		
	EL0611		15,000	-	-		$I_F = 7.5 \text{mA}$, $V_{OL} = 0.8 \text{V}$, $R_L = 350 \Omega$, $TA = 25 ^{\circ}\text{C}$ $V_{CM} = 400 \text{Vp-p}$ (Fig.15)



Typical Electro-Optical Characteristics Curves





Note: The graphs shown in this datasheet are representing typical data only and do not show guaranteed values

Fig. 12 Test circuit and waveforms for tPHL, tPLH, tr, and tf

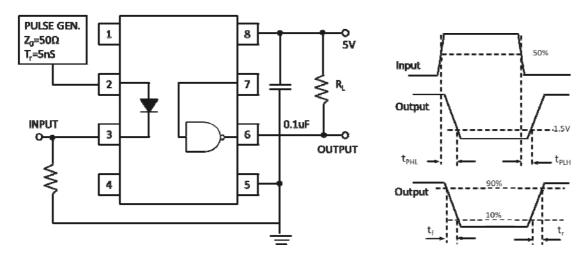


Fig. 13 Test circuit and waveform for tehland telh

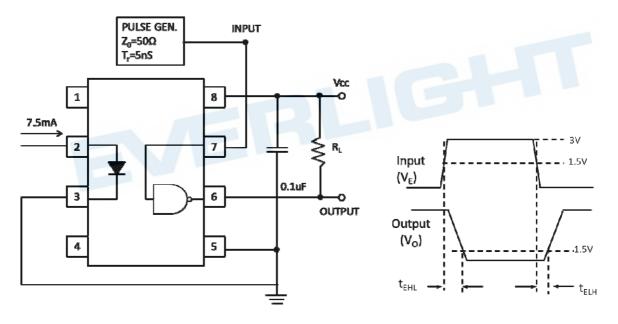




Fig. 14 Test circuit Common mode Transient Immunity

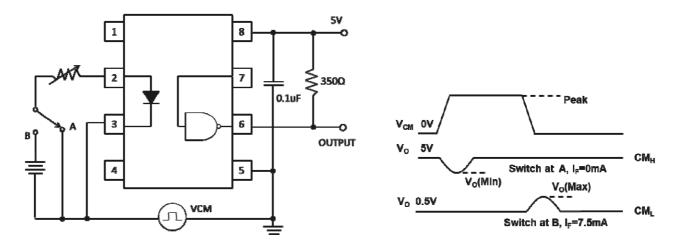
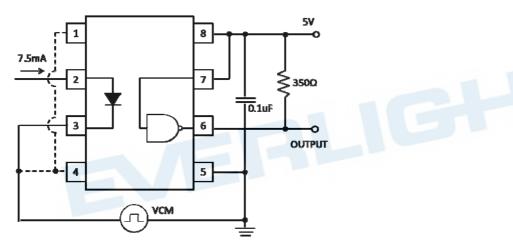


Fig. 15 Recommended drive circuit for EL0611 families for high-CMR



Notes

- *3. The V_{CC} supply must be bypassed by a 0.1µF capacitor or larger. This can be either a ceramic or solid tantalum capacitor with good high frequency characteristic and should be connected as close as possible to the package V_{CC} and GND pins
- *4. Enable Input No pull up resistor required as the device has an internal pull up resistor.
- *5. t_{PLH} Propagation delay is measured from the 3.75mA level on the HIGH to LOW transition of the input current pulse to the 1.5 V level on the LOW to HIGH transition of the output voltage pulse.
- *6. t_{PHL} Propagation delay is measured from the 3.75mA level on the LOW to HIGH transition of the input current pulse to the 1.5 V level on the HIGH to LOW transition of the output voltage pulse.
- *7. tr Rise time is measured from the 90% to the 10% levels on the LOW to HIGH transition of the output pulse.
- *8. tf Fall time is measured from the 10% to the 90% levels on the HIGH to LOW transition of the output pulse.
- *9. t_{ELH} Enable input propagation delay is measured from the 1.5V level on the HIGH to LOW transition of the input voltage pulse to the 1.5V level on the LOW to HIGH transition of the output voltage pulse.
- *10. t_{EHL} Enable input propagation delay is measured from the 1.5V level on the LOW to HIGH transition of the input voltage pulse to the 1.5V level on the HIGH to LOW transition of the output voltage pulse.
- *11 CM_H- The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the HIGH state (i.e., $V_{OUT} > 2.0V$).
- *12 CM $_L$ The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the LOW output state (i.e., $V_{OUT} < 0.8V$).



Order Information

Part Number

EL06XX(Z)-V

Note

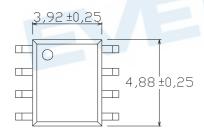
X = Part no. (X = 00, 01 or 11)

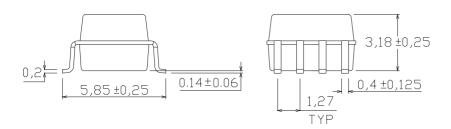
Z = Tape and reel option (TA, TB).

V = VDE (optional)

Option	Description	Packing quantity
(TA)	TA tape & reel option	2000 units per reel
(TB)	TB tape & reel option	2000 units per reel
(TA)-V	TA tape & reel option + VDE	2000 units per reel
(TB)-V	TB tape & reel option + VDE	2000 units per reel

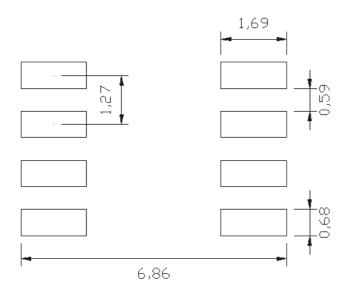
Package Dimension (Dimensions in mm)







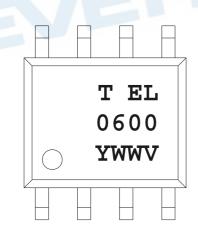
Recommended pad layout for surface mount leadform



Notes

Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

Device Marking



Notes

T denotes Factory

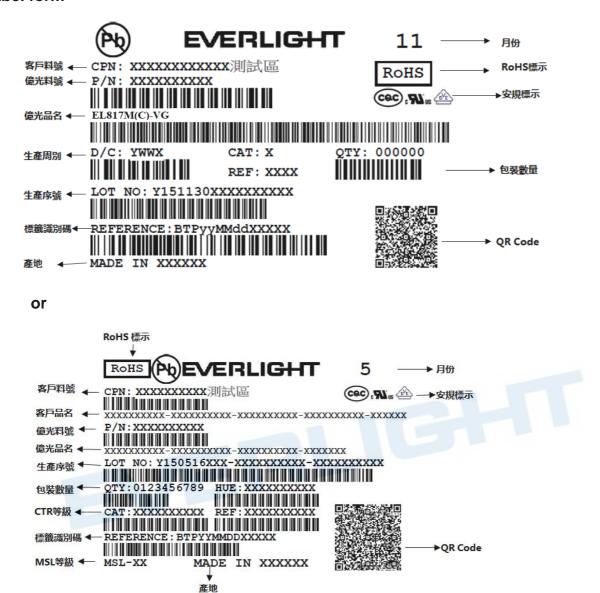
No code : made in China

T : made in Taiwan

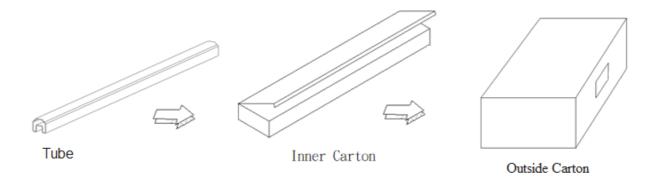
EL denotes EVERLIGHT
0600 denotes Device Number
Y denotes 1 digit Year code
WW denotes 2 digit Week code
V denotes VDE (optional)



Label form

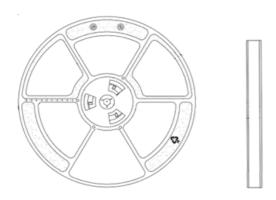


TUBE Dimension

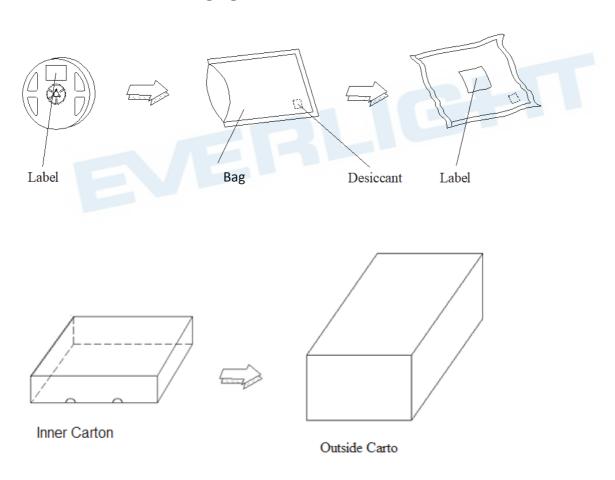




Reel Dimension



Moisture Resistant Packaging

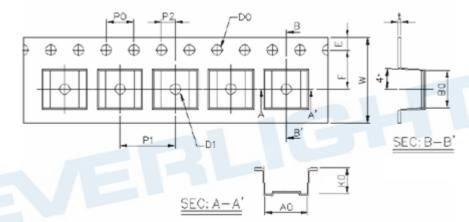




Tape & Reel Packing Specifications

Option TA Option TB Option TB Option TB Option TB Direction of feed from reel Option TB Option TB Option TB

Tape dimension



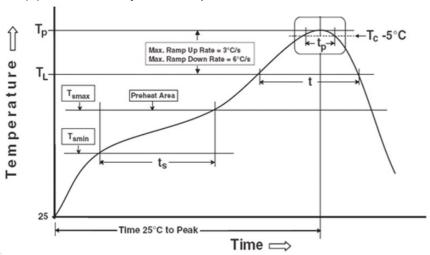
Dimension No.	Α0	В0	D0	D1	E	F
Dimension(mm)	6.2±0.1	5.26±0.1	1.5±0.1	1.5±0.3	1.75±0.1	5.5±0.1
Dimension No.	Ро	P1	P2	t	w	K0
Dimension(mm)	4.0±0.1	8.0±0.1	2.0±0.1	0.25±0.1	12.0+0.3/ -0.1	3.75±0.1



Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Preheat

Temperature min (T_{smin})

Temperature max (T_{smax})

Time (T_{smin} to T_{smax}) (t_s)

Average ramp-up rate (T_{smax} to T_p)

Other

Liquidus Temperature (T_L)

Time above Liquidus Temperature (t L)

Peak Temperature (T_P)

Time within 5 °C of Actual Peak Temperature: TP - 5°C

Ramp- Down Rate from Peak Temperature

Time 25°C to peak temperature

Reflow times

Reference: IPC/JEDEC J-STD-020D

150 °C

200°C

60-120 seconds

3 °C/second max

217 °C

60-100 sec

260°C

30 s

6°C /second max.

8 minutes max.

3 times



Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5°C to 35°C and 20 % to 60 %,respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use





DISCLAIMER

- 1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- 2. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 3. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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